

FIG. 1

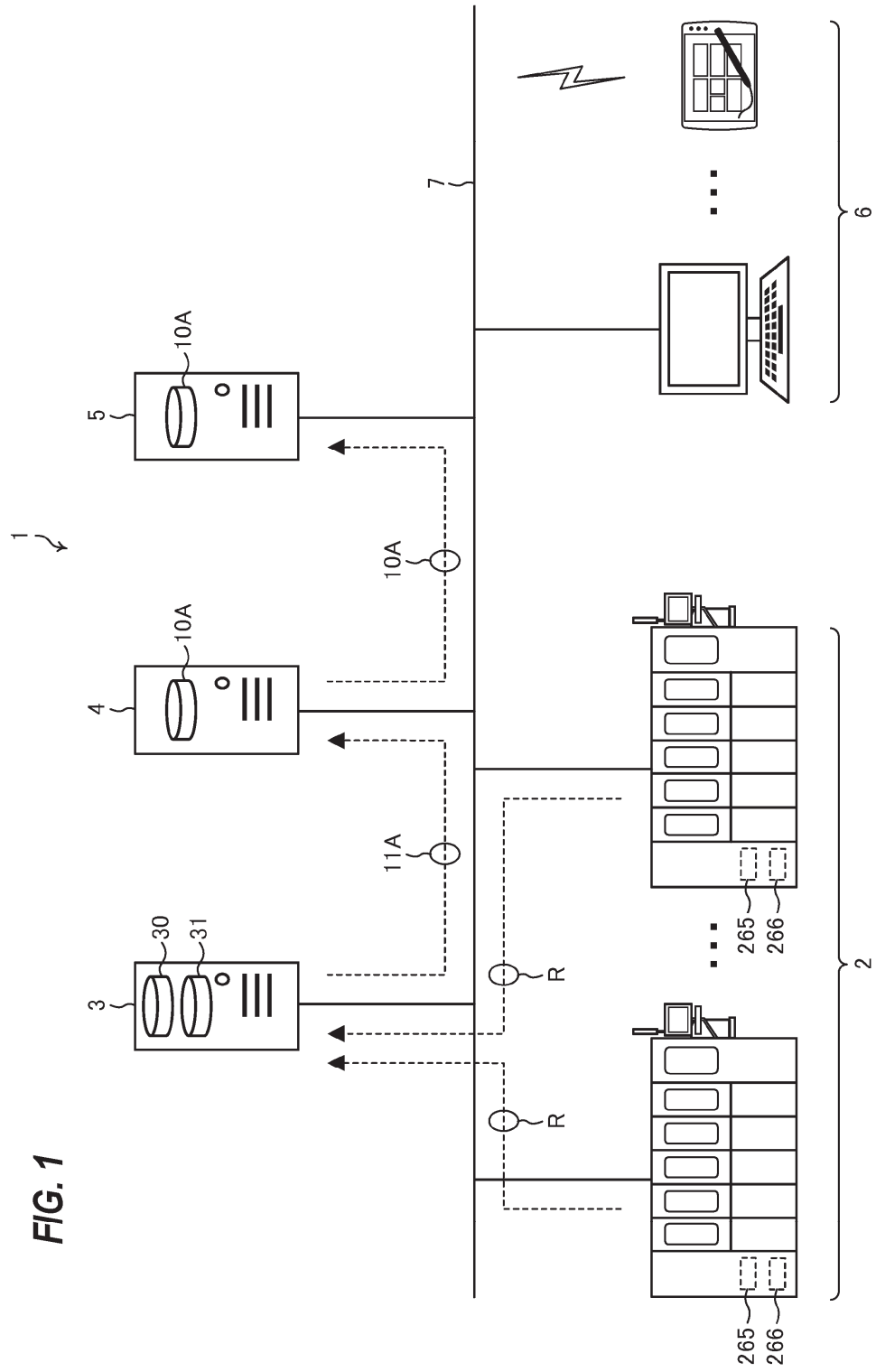
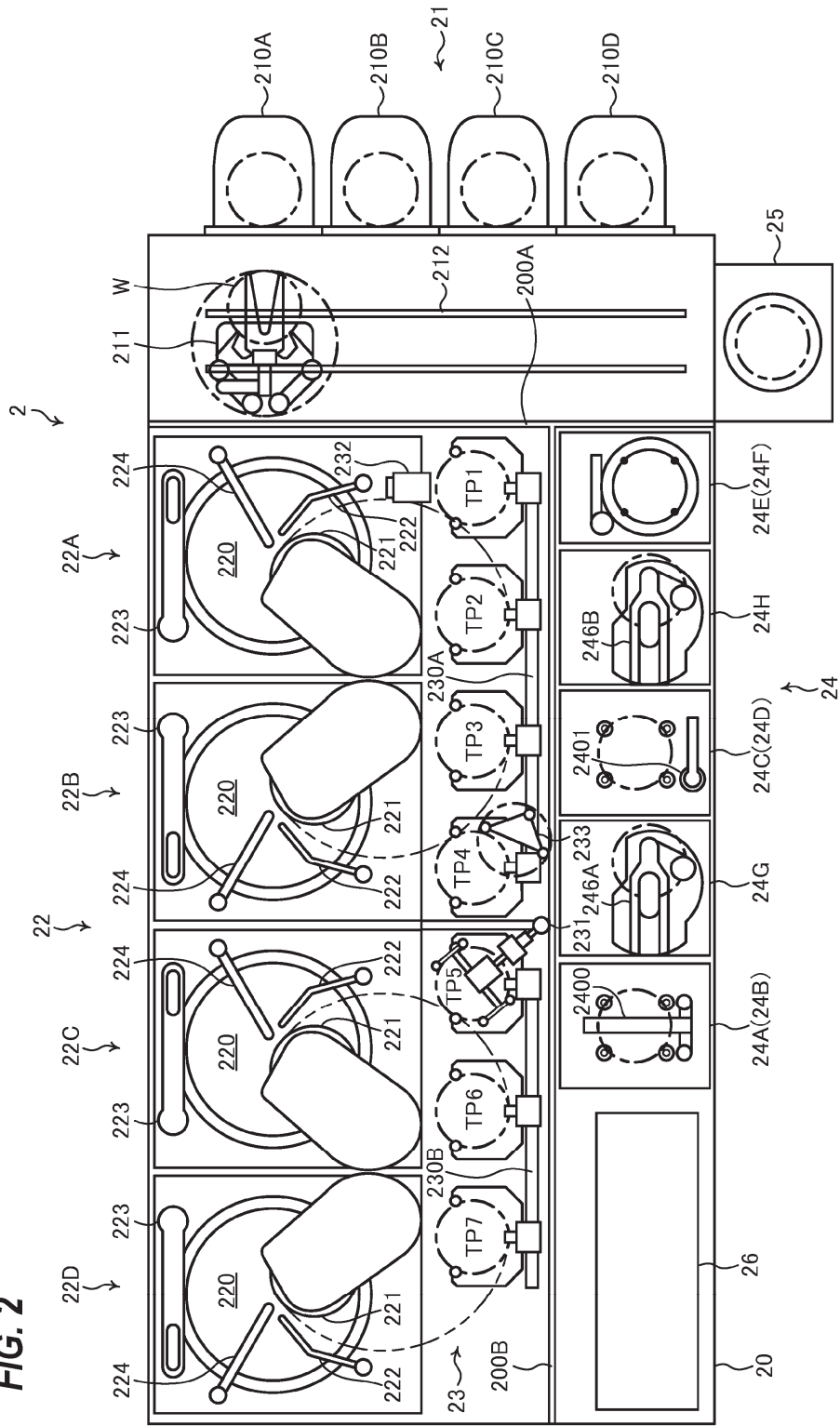


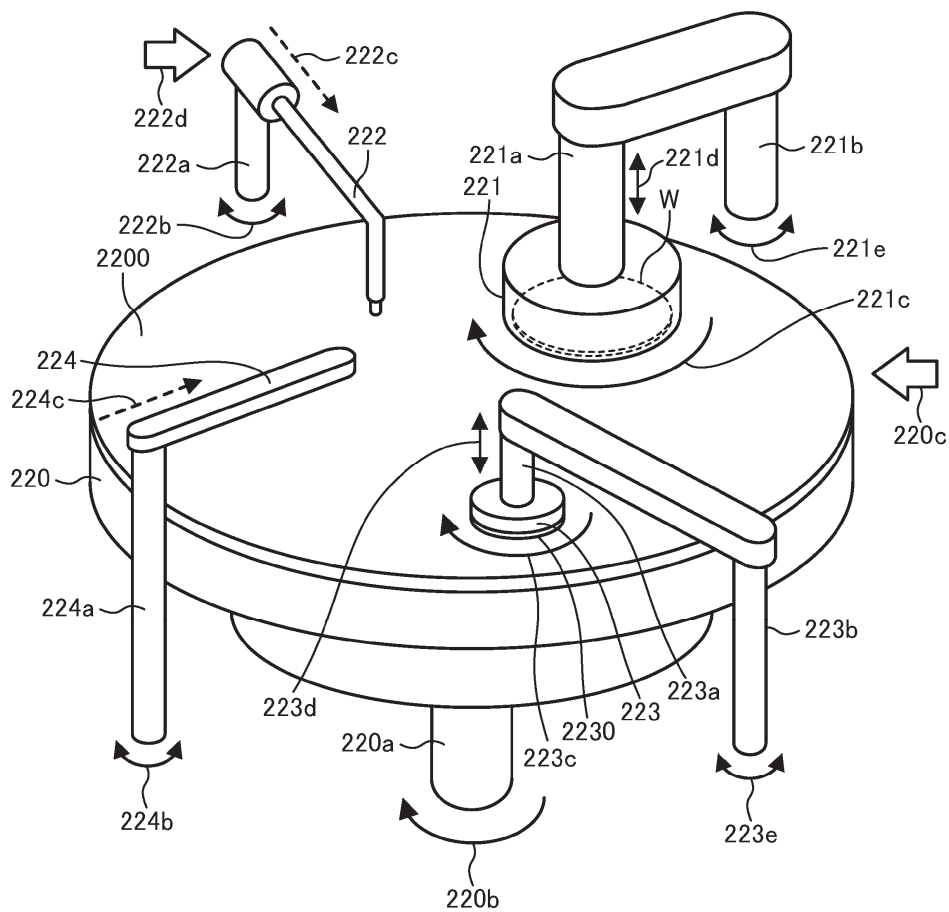
FIG. 2



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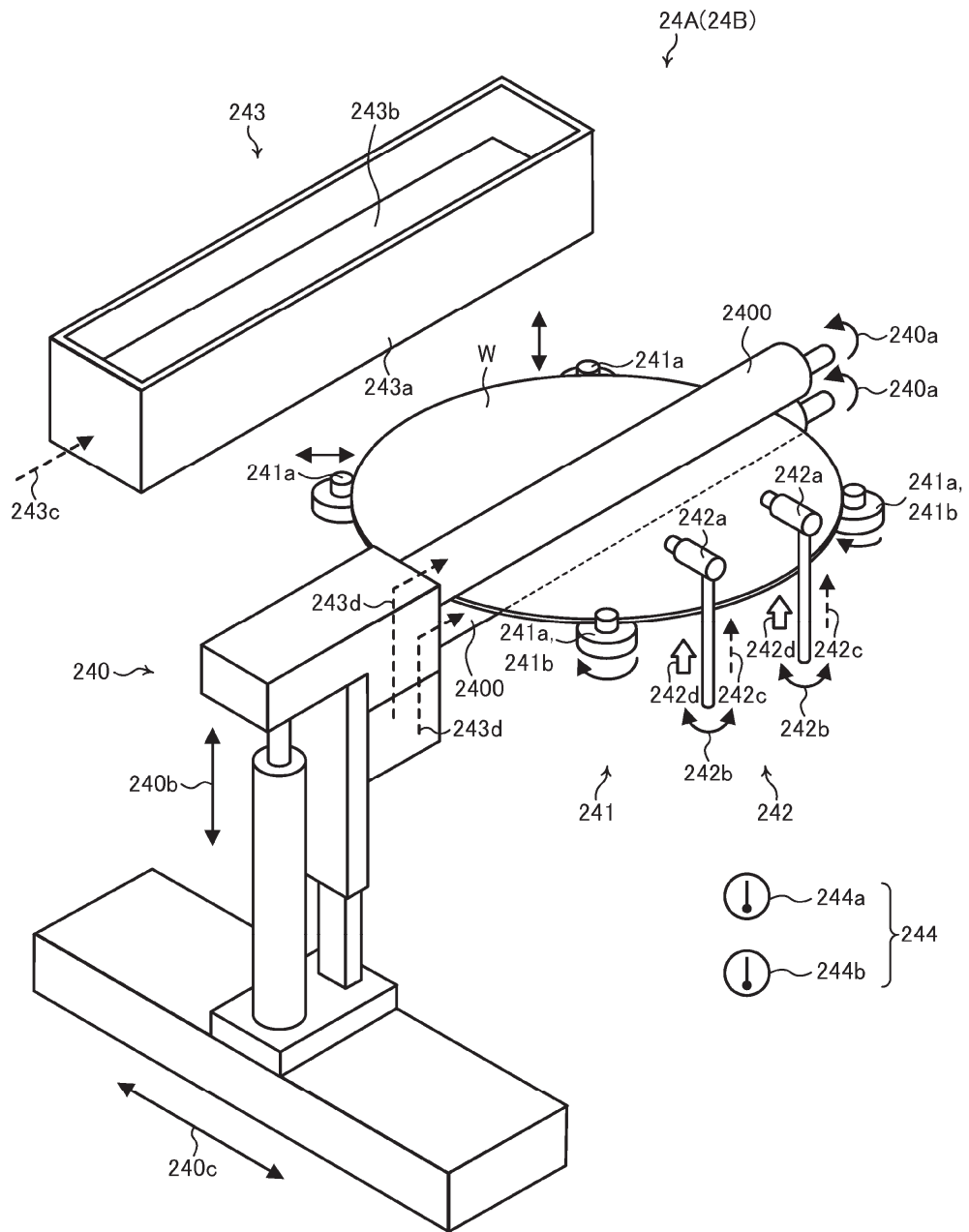
FIG. 3

22A(22B~22D)



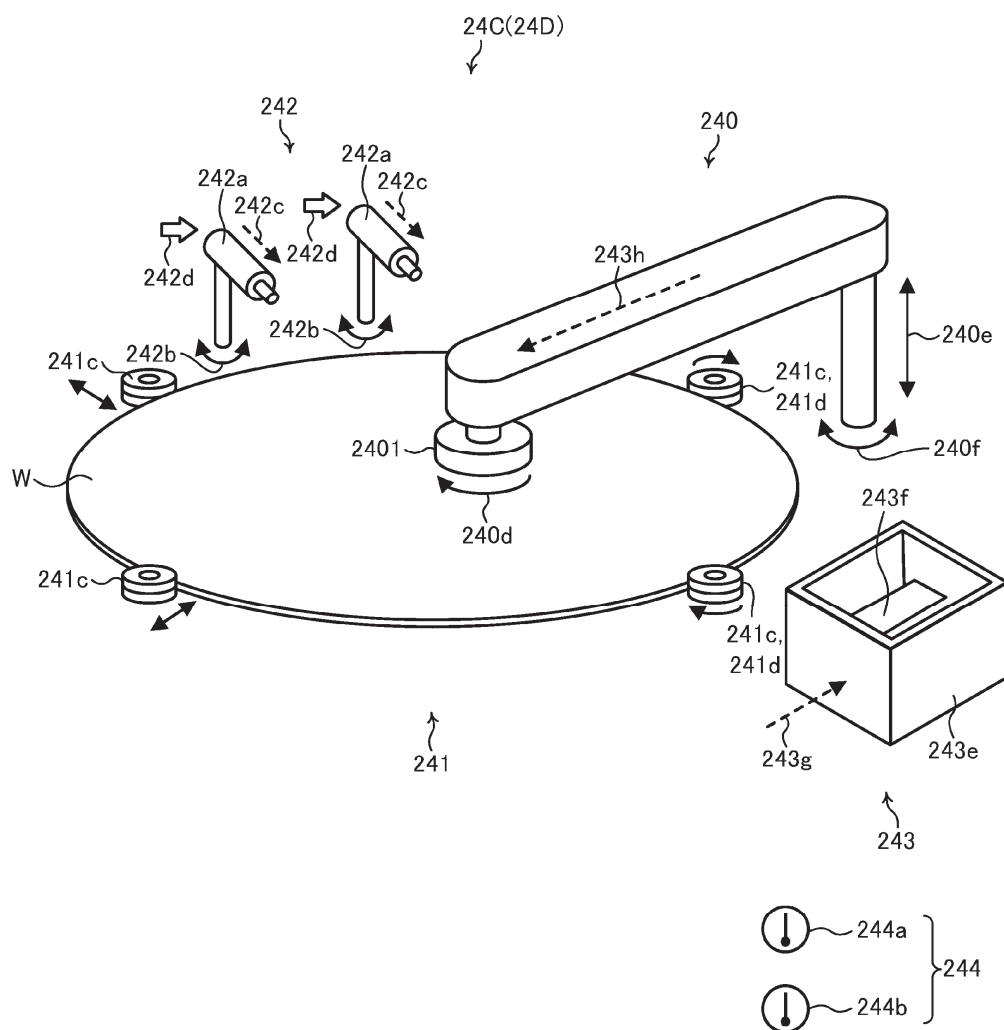
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FIG. 4



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FIG. 5



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FIG. 6

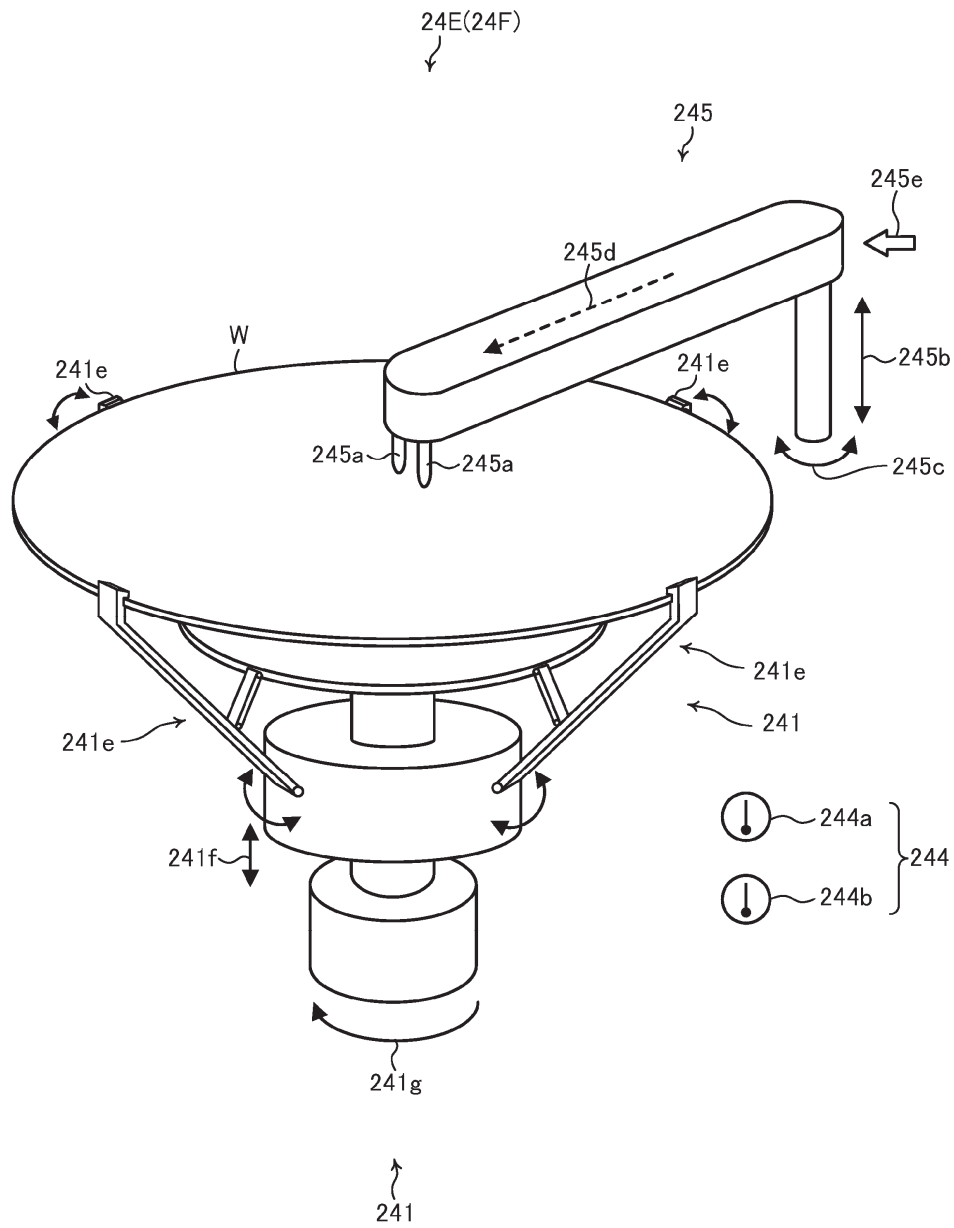
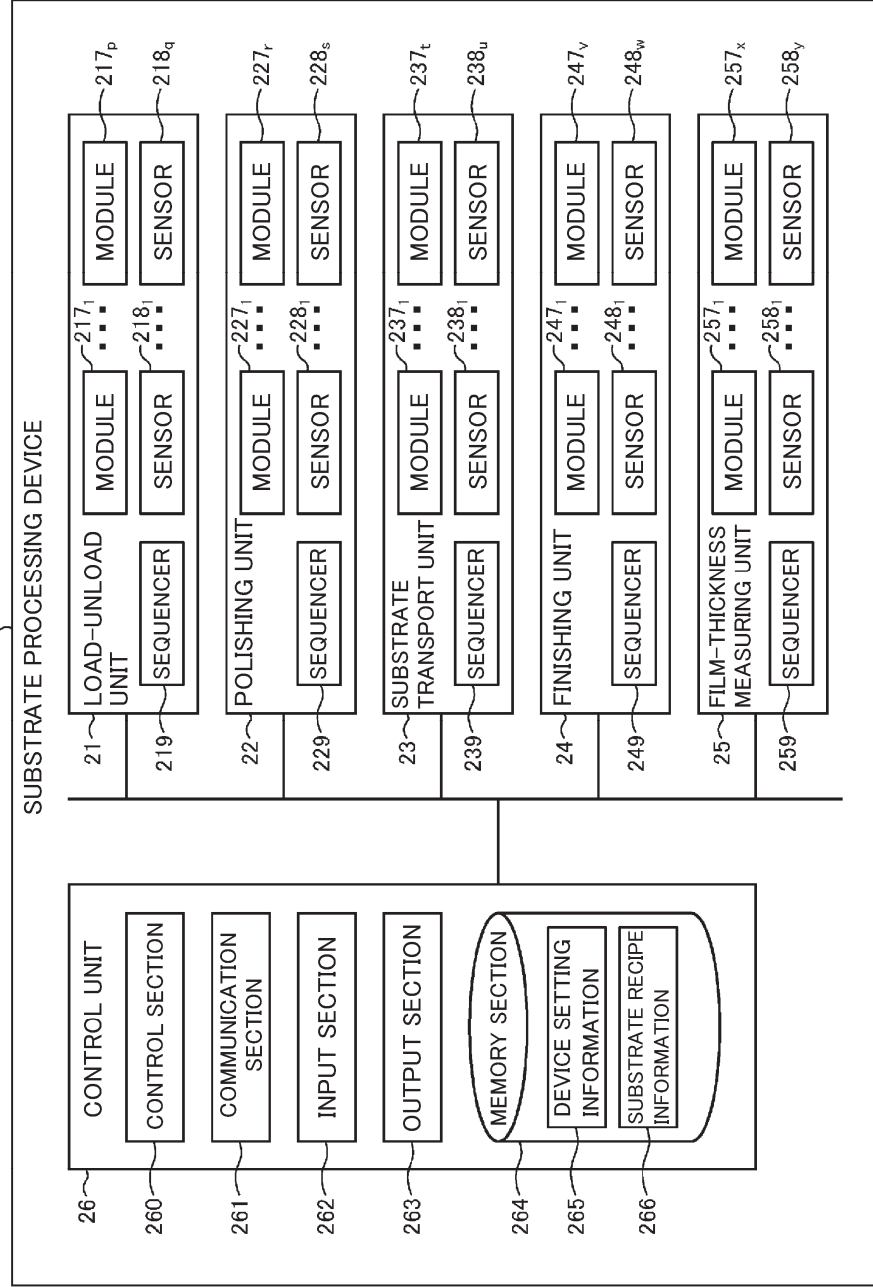


FIG. 7



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FIG. 8

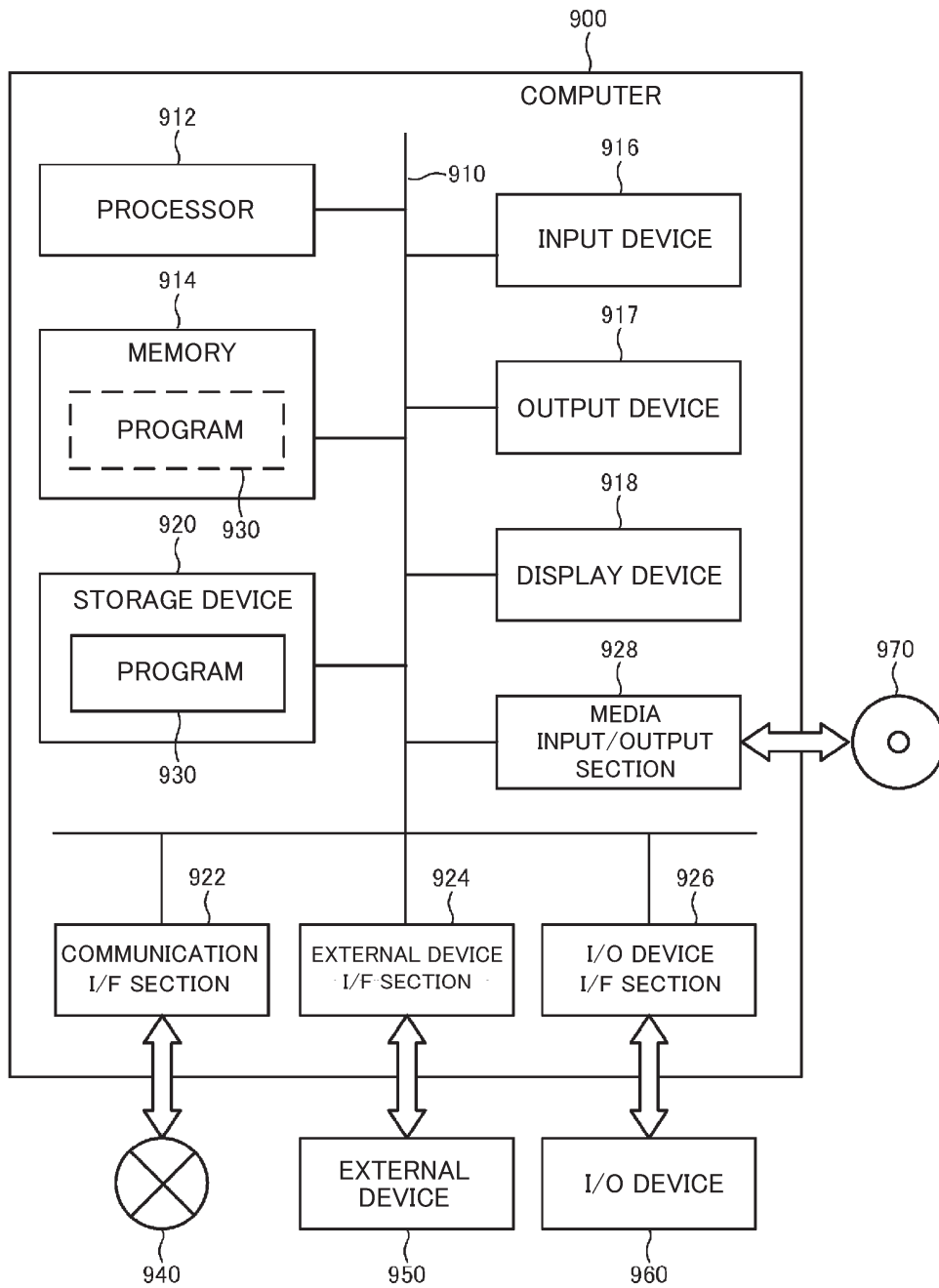


FIG. 9

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No	WAFER ID	CASSETTE NUMBER	SLOT NUMBER	POLISHING PROCESS		
				START TIME	END TIME	USED UNIT ID
1	W111	C01	S12	P_St_111	P_End_111	PA, LTP1
2	W222	C02	S08	P_St_222	P_End_222	PC, LTP2
...	...	...	...	...	...	...

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No	WAFER ID	SUBSTRATE ROTATION SPEED INFORMATION	SUBSTRATE ROTATION TORQUE INFORMATION	SUBSTRATE HOLDING POSITION INFORMATION	SUBSTRATE PRESSING LOAD INFORMATION
1	W111	WA_Data_111	WB_Data_111	WC_Data_111	WD_Data_111
2	W222	WA_Data_222	WB_Data_222	WC_Data_222	WD_Data_222
...	...	...	...	...	...

CLEANING PROCESS				DRYING PROCESS			
START TIME	END TIME	USED UNIT ID	USED UNIT ID	START TIME	END TIME	USED UNIT ID	USED UNIT ID
C_St_111	C_End_111	CA	CA	D_St_111	D_End_111	DA	DA
C_St_222	C_End_222	CB	CB	D_St_222	D_End_222	DB	DB
...	...	...	...	...	...	...	...

FIG. 10

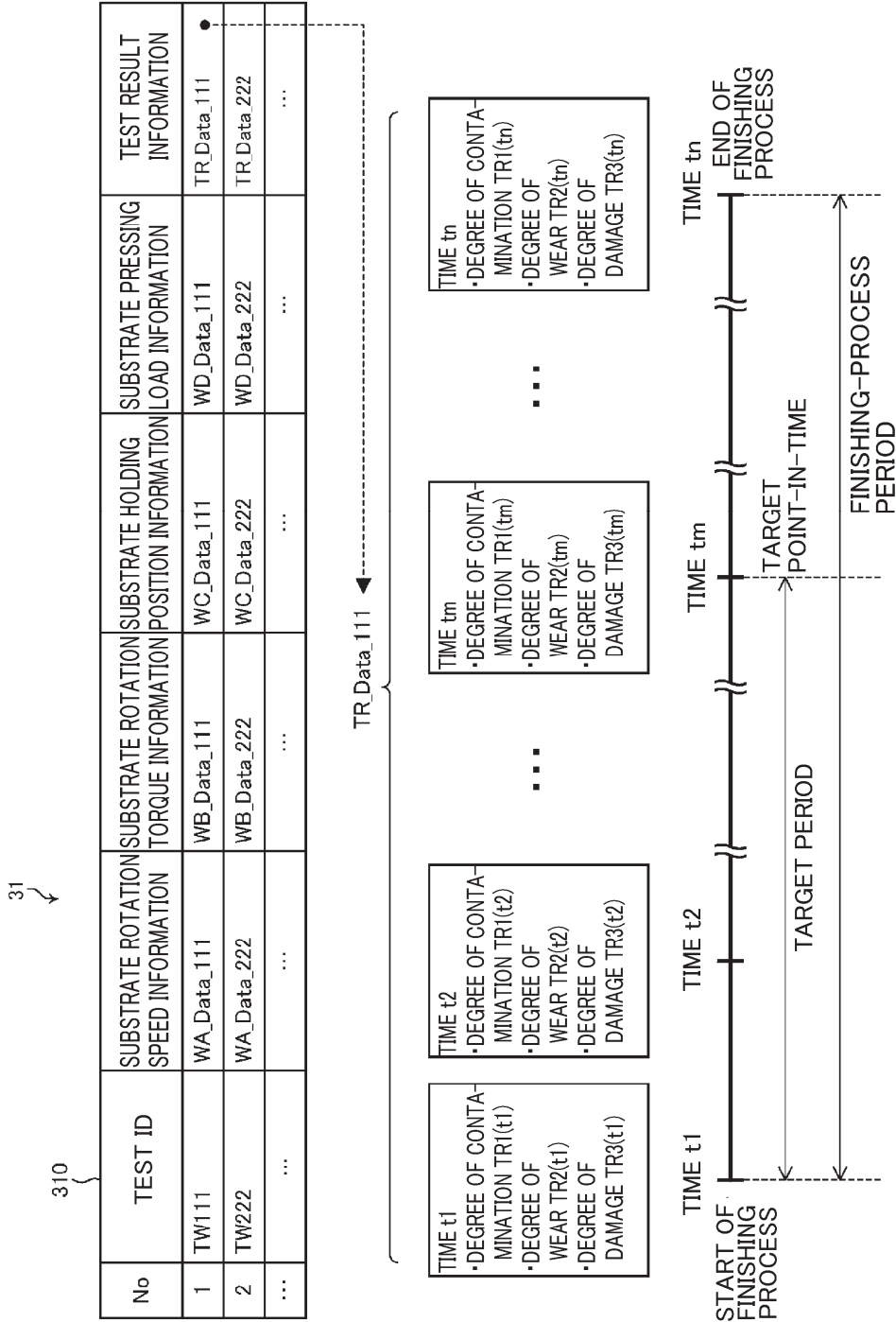


FIG. 11

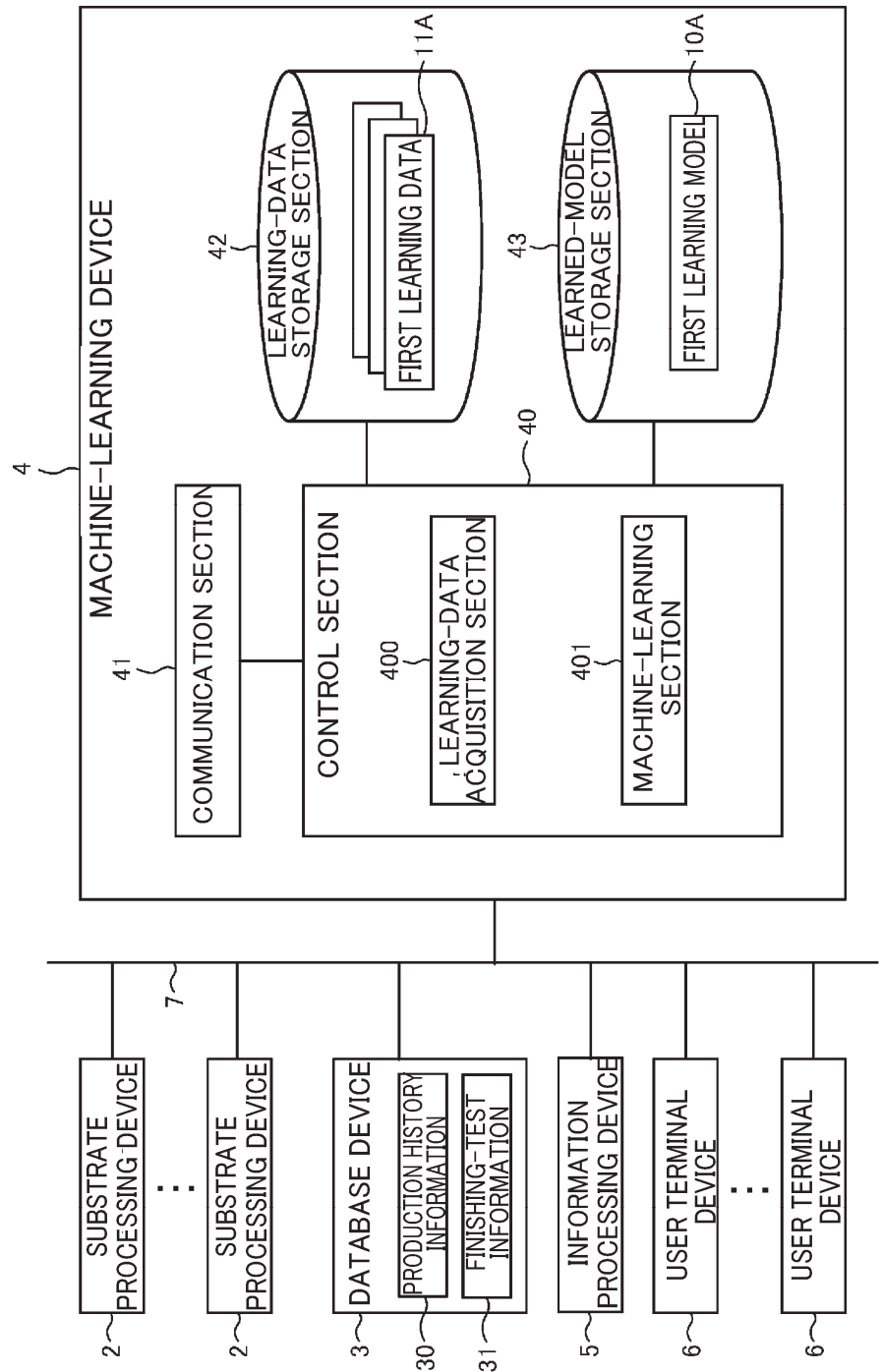


FIG. 12

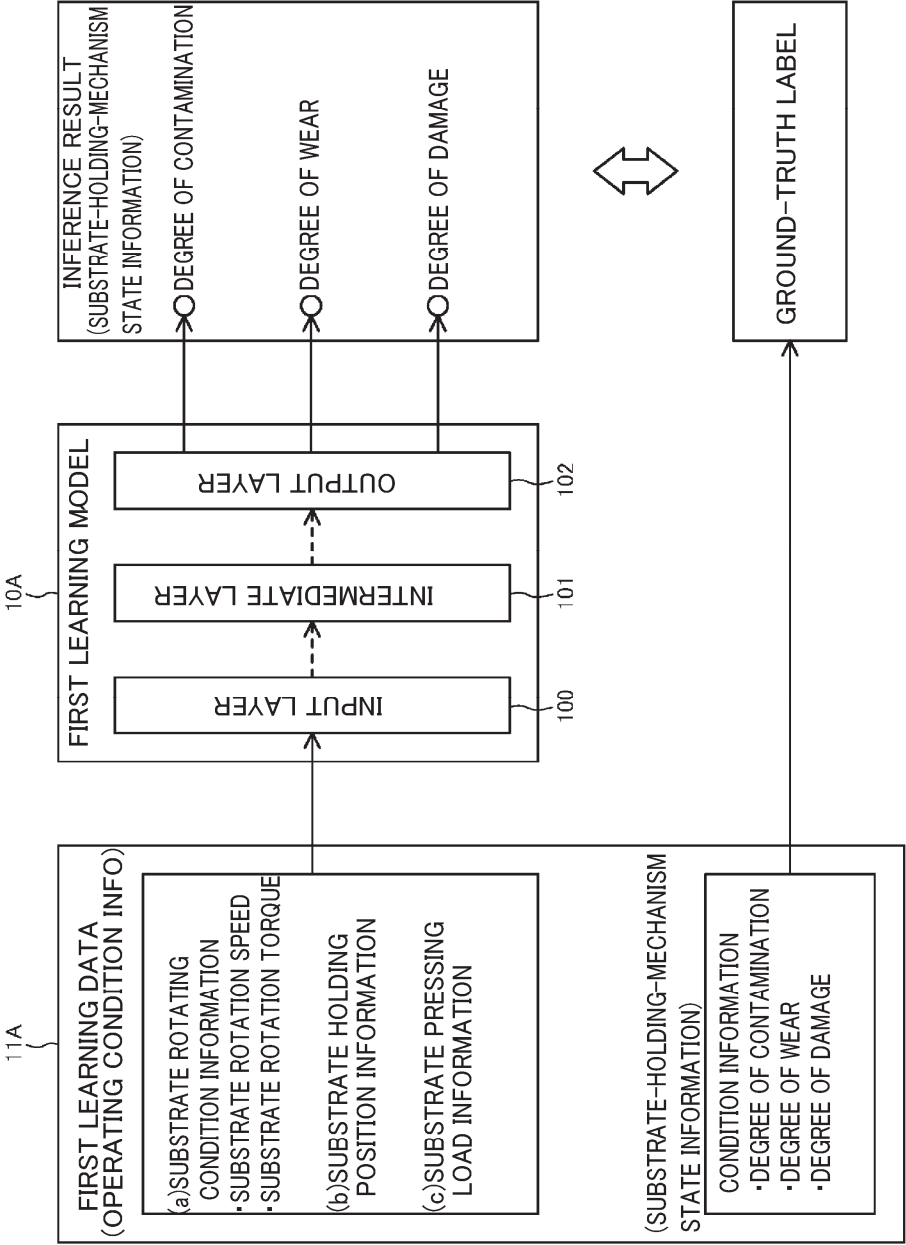


FIG. 13

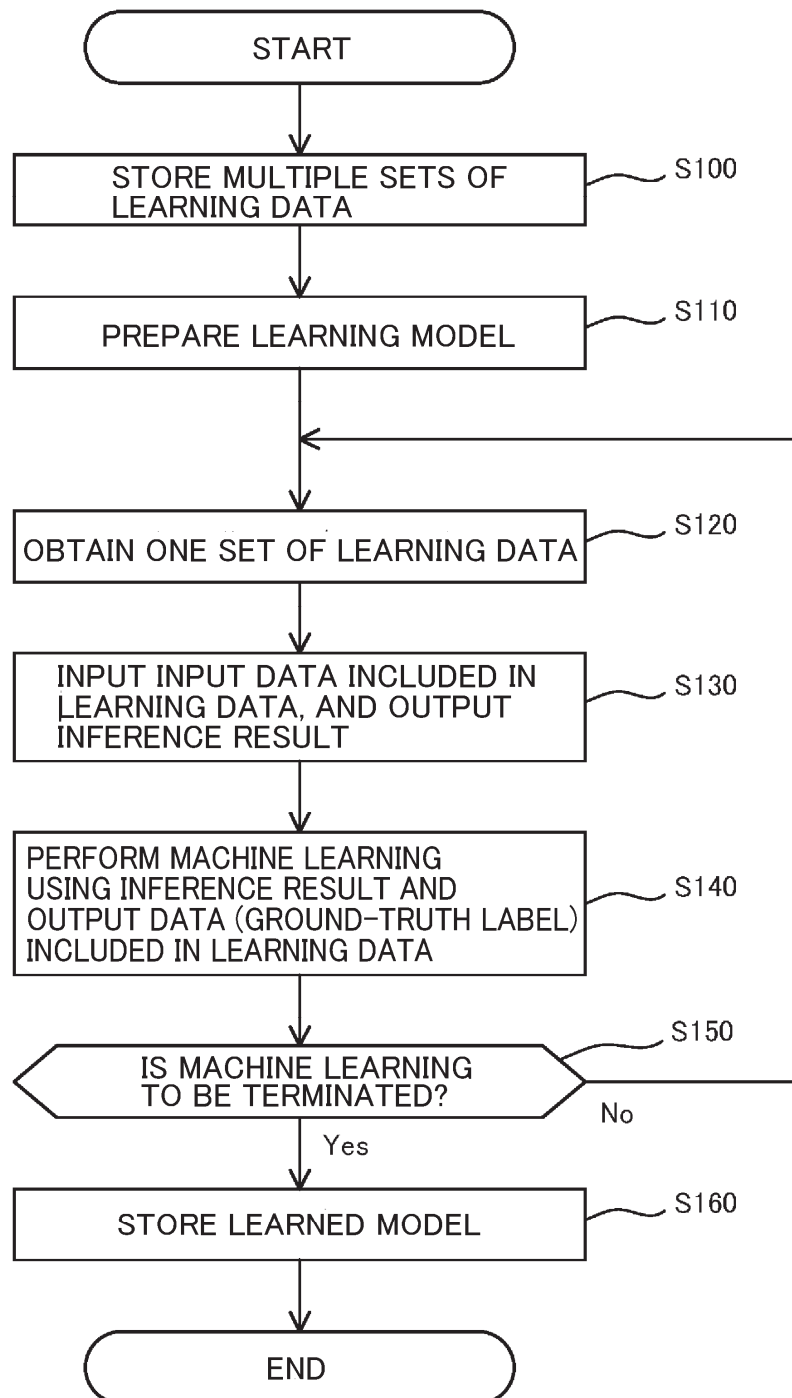


FIG. 14

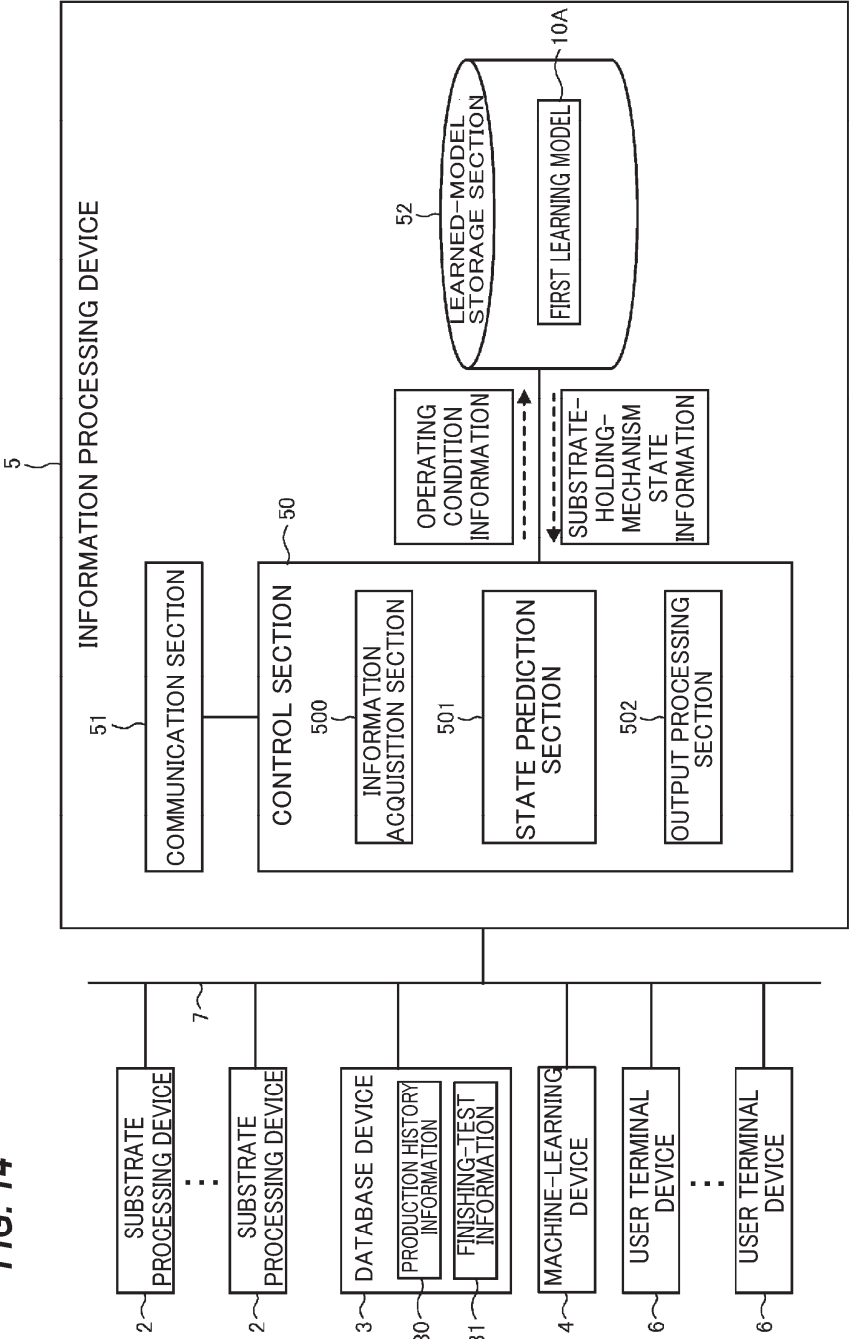
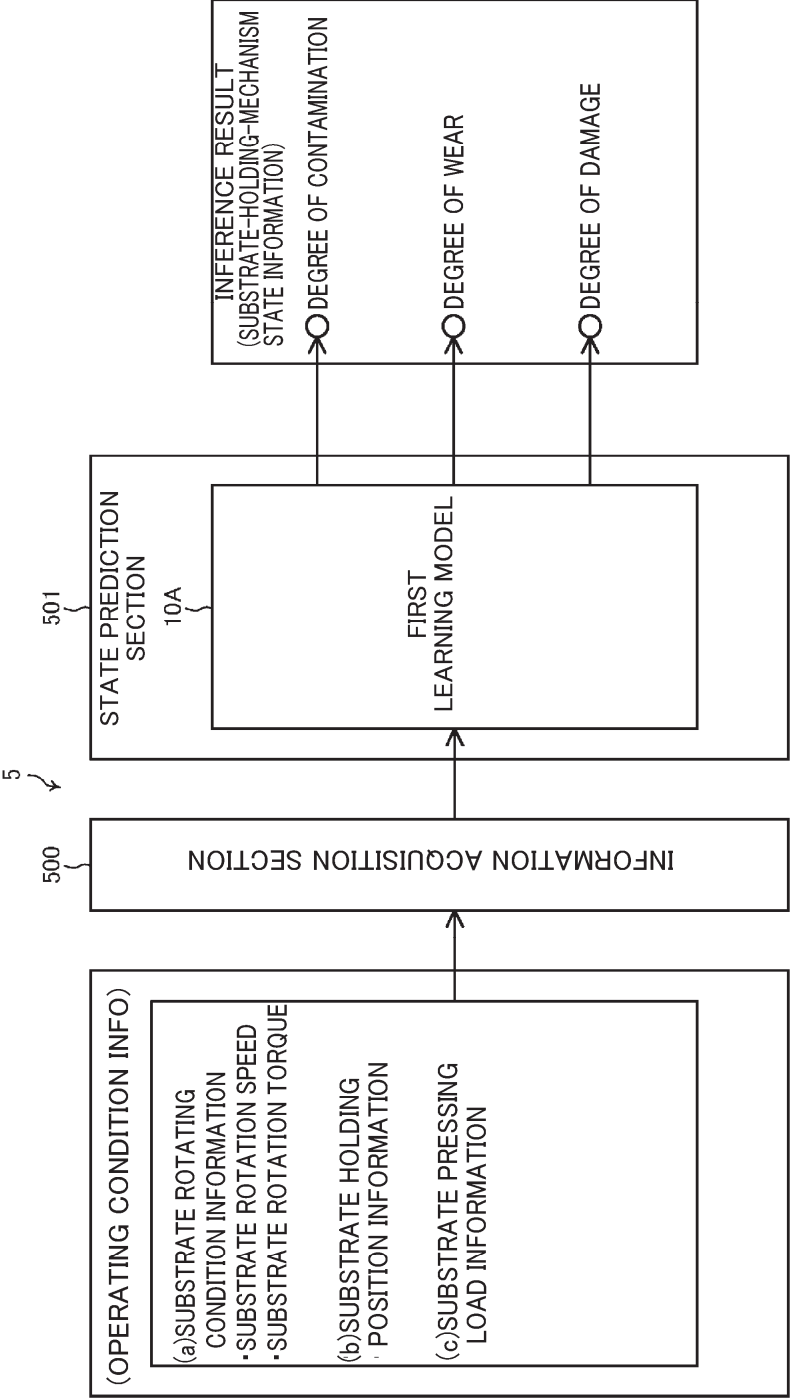


FIG. 15



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FIG. 16

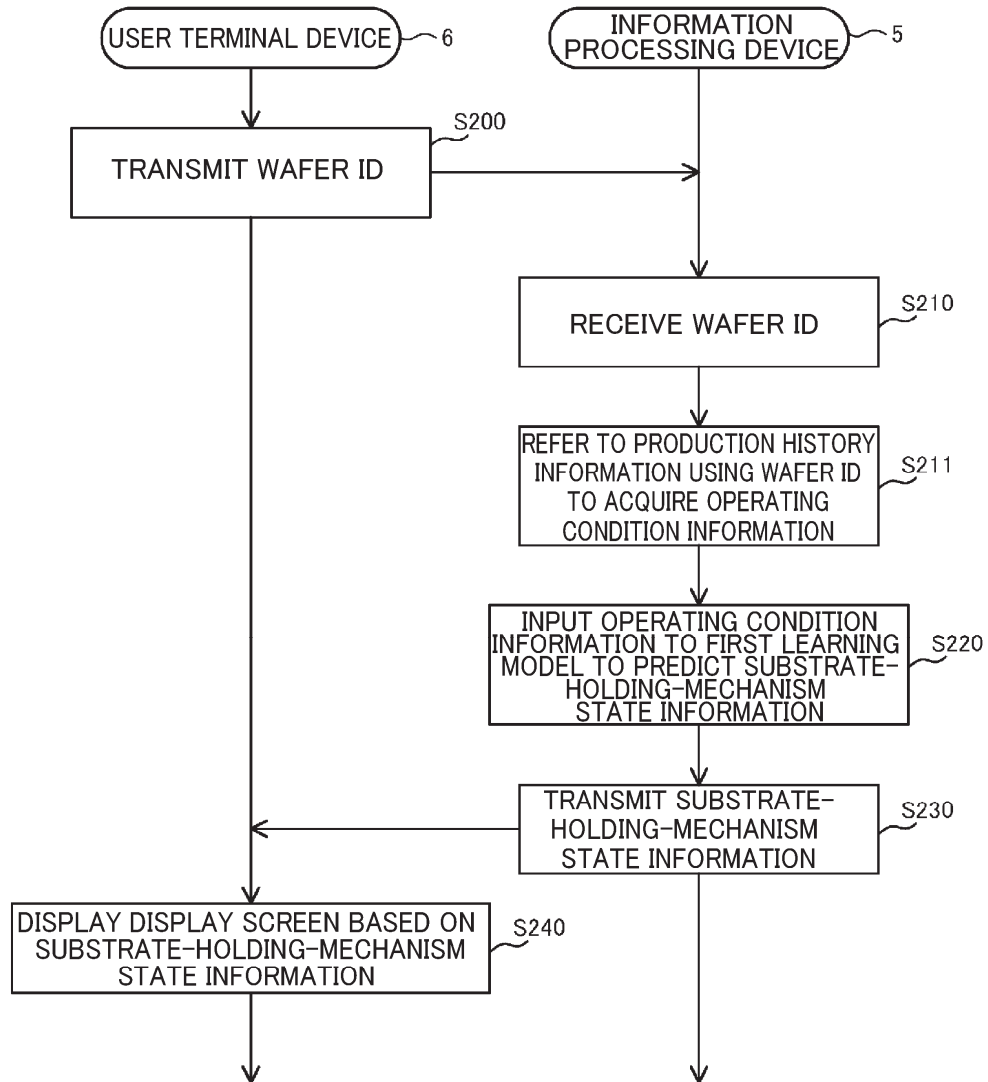


FIG. 17

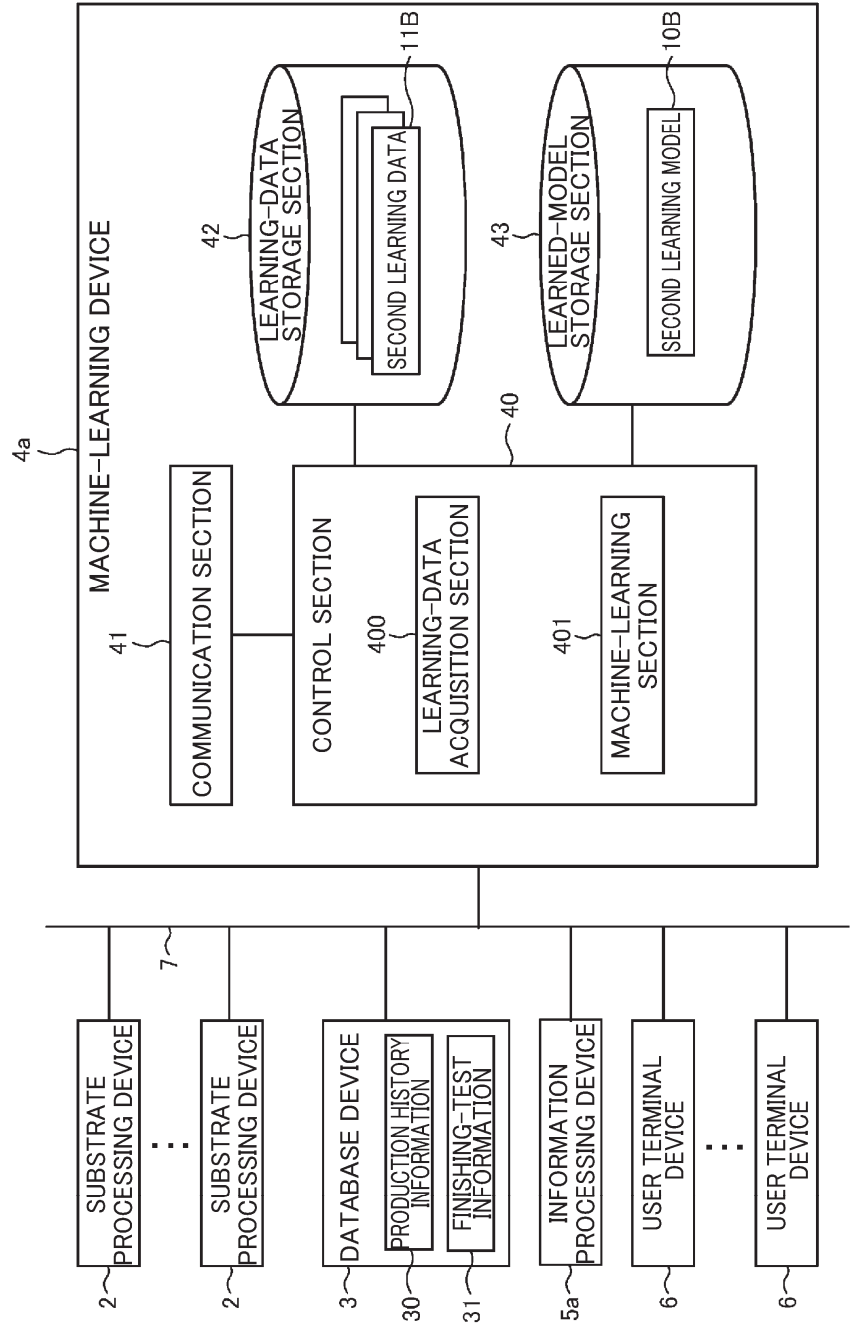


FIG. 18

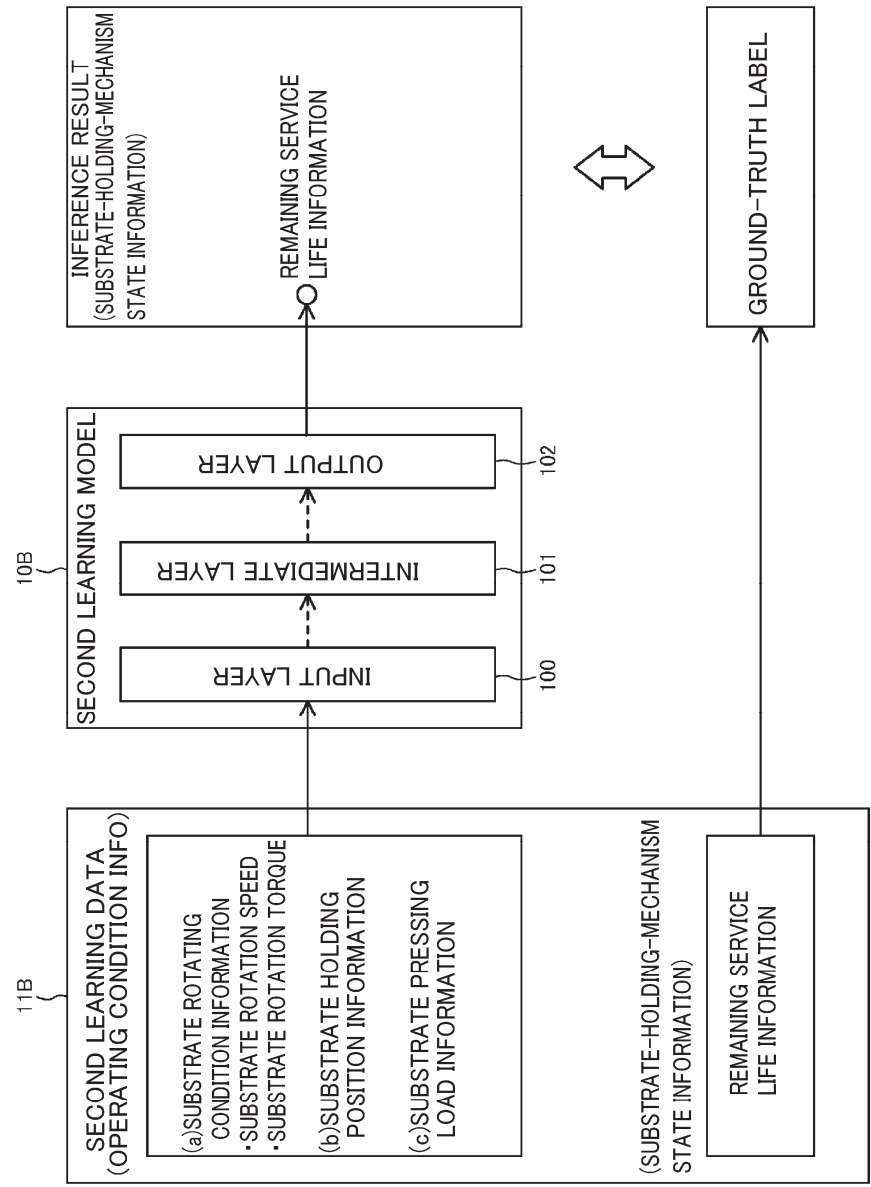


FIG. 19

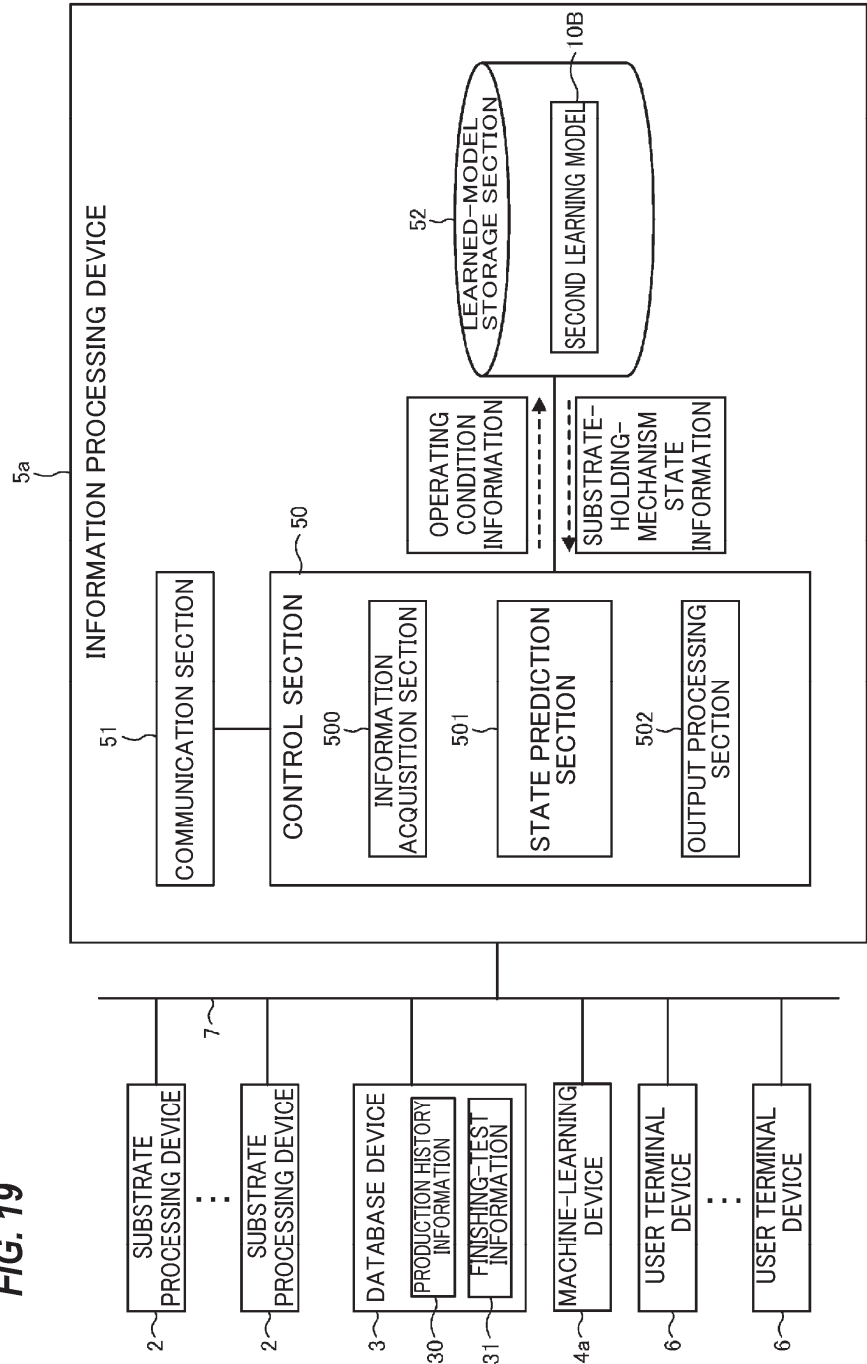


FIG. 20

